

MAIL STOP AF  
PATENT  
8007-1116

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of

Takashi SUEYOSHI et al.

Conf. 1846

Application No. 10/594,221

Group 1796

Filed September 25, 2006

Examiner O. Ojurongbe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED  
PRODUCT THEREOF

**AMENDMENT AFTER FINAL REJECTION**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

March 9, 2009

Sir:

In response to the Official Action mailed November 7, 2009, for which the period for response has been extended one month, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 5 of this paper.

An **Appendix** is attached which follows the signature page of this paper.